

Features:

- Lower density
- High breakdown voltage
- Good heat spreader
- High volume resistivity
- Good EMC
- Ideal for direct metalisation
- Good thermal cycling stability

Applications:

- Metal heat sink replacement, LED, Chipset cooling, power modules, IC cooling

Property		Units	Value
Physical	Material	N/A	Al ₂ O ₃
	Density	g/cm ³	3.66
	Water absorption	%	0.002
	Acid resistance	mg/cm ³	≤ 0.2
	Alkali resistance	mg/cm ³	≤ 0.2
Mechanical	Mohs hardness	HV	9
	Bend strength	MPa	≥610
	Compression intensity	MPa	≥620
Thermal	Max. working temp.	°C	1400
	Thermal expansion coefficient	(1×10 ⁻⁶) mm/ °C	7.8 - 8.3
	Thermal conductivity	W/m K	25
Electrical	Resisting rate of volume	Ω °C	1016
	DC breakdown strength	kV/mm	15.2 - 16.7
	Dielectric constant	(E)	18
	Dielectric dissipation	(tg o)	0.4 × 10 ⁻³

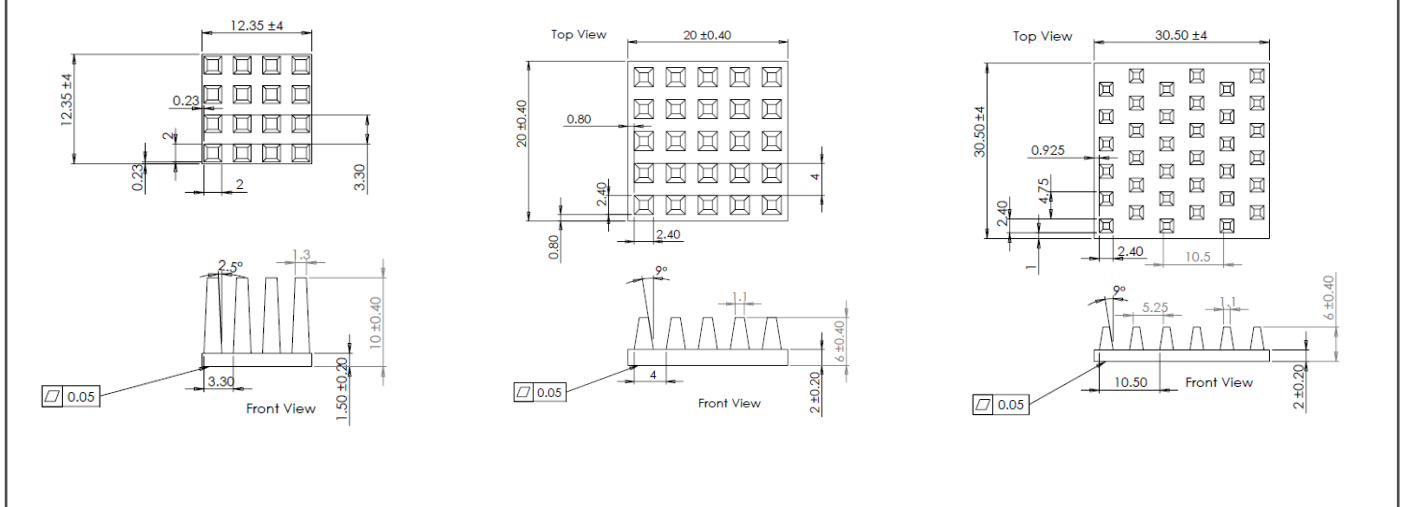
Part Number	Size	R _{th} (°C/W) at 100 lfm	R _{th} (°C/W) at 400 lfm	Dwg
SF-CHS-121210P	12x12x10mm	37.8	18.5	A
SF-CHS-202006P	20x20x6mm	40.0	23.7	B
SF-CHS303006P	30x30x6mm	26.7	15.7	C
SF-CHS-323206P	32x32x6mm	22.4	13.2	D
SF-CHS-434306P	43x43x6mm	12.2	7.5	E
SF-CHS-606015P	60x60x15mm	5.2	2.4	F

Drawing layouts:

Drawing A: 12x12x10mm

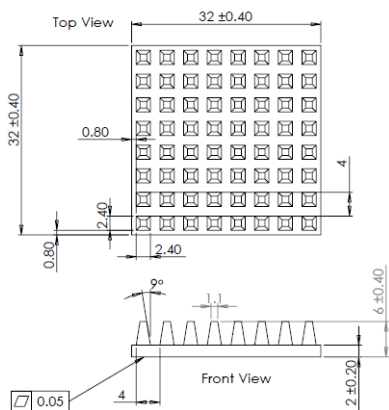
Drawing B: 20x20x6mm

Drawing C: 30x30x6mm

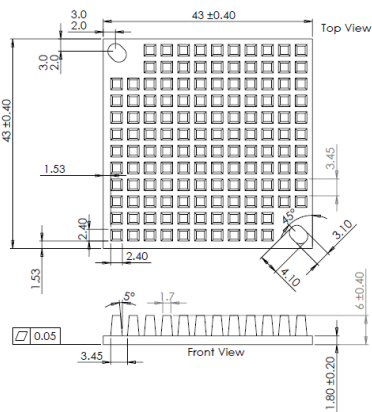


Drawing layouts:

Drawing D: 32x32x6mm



Drawing E: 43x43x6mm



Drawing F: 60x60x15mm

